



Zaawansowane Systemy Trójwymiarowe: Proces i Technologia Stacking IC

Indeks: **717502** Producent: **Springer** Kod producenta: **biography**

Cena: **227.63 zł**

Opis

Three Dimensional System Integration: IC Stacking Process and Design

Producent: Springer

- **temat:** Building construction & materials, Circuits & components, ARCHITECTURE / Methods & Materials, Architecture/Methods & Materials, Computers/Design, Graphics & Media - CAD-CAM, Technology & Engineering / Construction / Heating, Ventilation & Air Conditioning, Technology & Engineering / Electronics / Circuits / General, Technology & Engineering/Construction - Heating, Ventilation & Air Conditioning, Technology & Engineering/Electronics - Circuits - General, 3D Chip Stacking, 3D Chip Stacking; 3D Integrated Circuit Design and Manufacturing; 3D Integrated Circuits; 3D Stacked Integrated Circuits; 3D System Integration; Contactless 3D Coupling; DRAM Stacking; Logic Stacking; TSV; Through-Silicon Vias, 3D Chip Stacking;3D Integrated Circuit Design and Manufacturing;3D Integrated Circuits;3D Stacked Integrated Circuits;3D System Integration;Contactless 3D Coupling;DRAM Stacking;Logic Stacking;TSV;Through-Silicon Vias, 3D Integrated Circuit Design and Manufacturing, 3D Integrated Circuits, 3D Stacked Integrated Circuits, 3D System Integration, ANF: House and Home, ARCHITECTURE / Methods & Materials, Architecture, Architecture/Methods & Materials, Bautechnik, Umwelttechnik, Building Construction and Design, Building construction & materials, Building construction and materials, Circuits, Circuits & components, Computers, Computers/Design, Graphics & Media - CAD-CAM, Construction, Construction - Heating, Ventilation & Air Conditioning, Contactless 3D Coupling, DRAM Stacking, Design, Graphics & Media - CAD-CAM, Electronic Circuits and Systems, Electronics, Electronics - Circuits - General, Electronics: circuits and components, Elektronik, Elektrotechnik, Nachrichtentechnik, General, HC, HC/Technik/Bautechnik, Umwelttechnik, HC/Technik/Elektronik, Elektrotechnik, Nachrichtentechnik, Hardcover, Softcover, Hardcover, Softcover / Technik/Bautechnik, Umwelttechnik, Heating, Ventilation & Air Conditioning, Hochbau und Baustoffe, Logic Stacking, Methods & Materials, Non-Fiction, Schaltkreise und Komponenten (Bauteile), Systems engineering, TECHNOLOGY & ENGINEERING, TECHNOLOGY & ENGINEERING / Construction / Heating, Ventilation & Air Conditioning, TECHNOLOGY & ENGINEERING / Electronics / Circuits / General, TEXT, TSV, Technik, Technology & Engineering/Construction - Heating, Ventilation & Air Conditioning, Technology & Engineering/Electronics - Circuits - General, Through-Silicon Vias, Verstehen, Building construction and materials, Electronics: circuits and components, Hochbau und Baustoffe, Schaltkreise und Komponenten (Bauteile), HC/Technik/Bautechnik, Umwelttechnik, HC/Technik/Elektronik, Elektrotechnik, Nachrichtentechnik, Hardcover, Softcover / Technik/Bautechnik, Umwelttechnik
- **wiązący:** paperback
- **język:** english, english, english
- **waga przedmiotu:** 454 grams
- **strony:** 256
- **słowo kluczowe tematu:** 3D Chip Stacking, 3D Chip Stacking; 3D Integrated Circuit Design and Manufacturing; 3D Integrated Circuits; 3D Stacked Integrated Circuits; 3D System Integration; Contactless 3D Coupling; DRAM Stacking; Logic Stacking; TSV; Through-Silicon Vias, 3D Chip Stacking;3D Integrated Circuit Design and Manufacturing;3D Integrated Circuits;3D Stacked Integrated Circuits;3D System Integration;Contactless 3D Coupling;DRAM

Stacking;Logic Stacking;TSV;Through-Silicon Vias, 3D Integrated Circuit Design and Manufacturing, 3D Integrated Circuits, 3D Stacked Integrated Circuits, 3D System Integration, Architecture, Contactless 3D Coupling, DRAM Stacking, Non-Fiction, TEXT

- **marka:** Springer
- **kod unspsc:** 55101500
- **kod podmiotu:** ARC009000, ARC009000, COM007000, TEC005050, TEC008010, TEC005050, TEC008010, 1685, 1684, 1685, TNK, TJFC, TNK, TJFC, TNK, TJFC
- **grupa docelowa:** Professional and scholarly
- **numer części:** biography
- **kolor:** White
- **waga opakowania przedmiotu:** 0.4672001411 kilograms
- **wydanie:** 2011
- **zewnętrznie przypisany identyfikator produktu:** 1489981829, 9781489981820, 09781489981820
- **producent:** Springer
- **gatunek muzyczny:** Building construction & materials, Circuits & components, TECHNOLOGY & ENGINEERING, Construction, Heating, Ventilation & Air Conditioning, TECHNOLOGY & ENGINEERING, Electronics, Circuits, General, HC, Technik, Bautechnik, Umwelttechnik, HC, Technik, Elektronik, Elektrotechnik, Nachrichtentechnik, Building construction and materials, Electronics: circuits and components
- **Data publikacji:** 2014-09-02T00:00:01Z
- **numer wydania:** 1
- **nazwa przedmiotu:** Three Dimensional System Integration: IC Stacking Process and Design
- **data premiery:** 2014-09-02T00:00:01Z
- **data uruchomienia strony produktu:** 2014-09-22T09:42:49.178Z

Parametry

Wydanie	2011
Rodzaj okładki	miękka